

Title (en)

SENSOR MODULE, PRODUCTION METHOD OF A SENSOR MODULE, AND INJECTION MOLD FOR ENCAPSULATING A SENSOR MODULE

Title (de)

SENSORMODUL, HERSTELLUNGSVERFAHREN EINES SENSORMODULS SOWIE SPRITZGIESSWERKZEUG ZUM UMGIESSEN EINES SENSORMODULS

Title (fr)

MODULE DÉTECTEUR, PROCÉDÉ DE PRODUCTION D'UN MODULE DÉTECTEUR ET MOULE DE COULÉE SOUS PRESSION POUR ENCAPSULER UN MODULE DÉTECTEUR

Publication

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Application

**EP 10790367 A 20101126**

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Abstract (en)

[origin: WO2011064347A2] The invention relates to a sensor module comprising a chip carrier and a sensor chip disposed thereon. A channel is formed between the chip carrier and the sensor chip, by means of which a medium can be fed to the sensor chip. The invention further relates to an injection mold for covering the sensor module, and to a production method for a covered sensor module.

IPC 8 full level

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